



## Precision Timing at the High Energy Frontier with the CMS MIP Timing Detector

Lake Louise Winter Institute 2023, 2.26.2023

Federico Siviero on behalf of the CMS MTD group







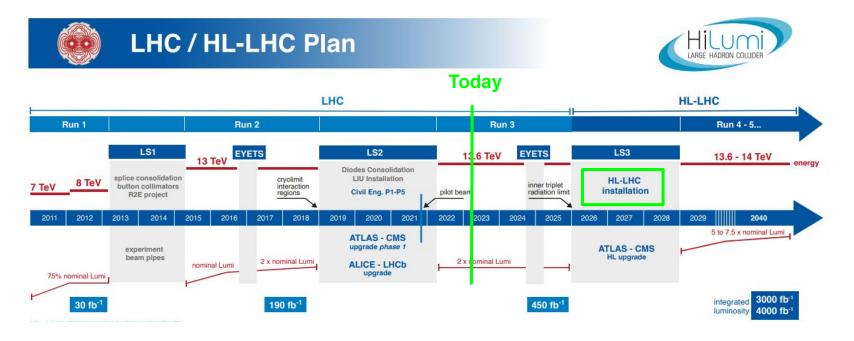
- > The CMS MIP Timing Detector
- Status of the Barrel Timing Layer
- Status of the Endcap Timing Layer







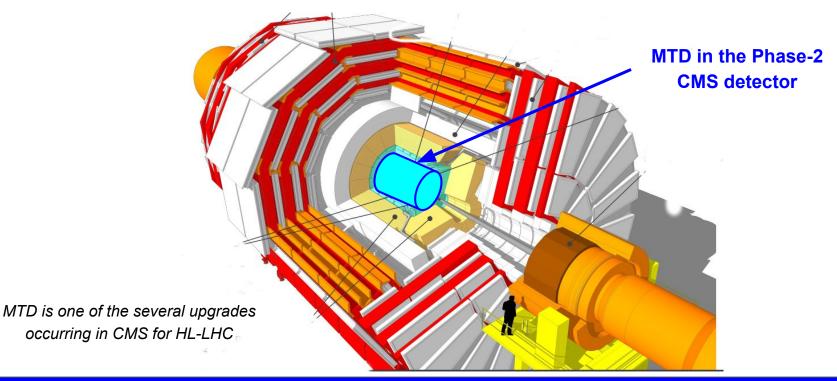
### > The CMS MIP Timing Detector







MTD will provide accurate timing of charged tracks during the High-Luminosity phase of the LHC (HL-LHC)







ETL ETL BTL

MTD will be divided in 2 sub-detectors

#### Barrel Timing Layer (BTL): LYSO + SiPM

- tracker / ECAL interface,  $|\eta| < 1.45$
- ~5 m long
- 38 m<sup>2</sup> surface, 332k channels
- Fluence @ end of life ~ 2e14 n<sub>ed</sub>/cm<sup>2</sup>

#### Endcap Timing Layer (ETL): LGAD

- ±3 m away from interaction point
- 0.31 m < R < 1.2 m
- $2x (7 \text{ m}^2)$  surface, ~8M channels
- Fluence @ end of life = up to ~ 2e15 n<sub>ed</sub>/cm<sup>2</sup>





ETL PP collision ETL

#### Key figure: time resolution per track

- ETL: < 35 ps
- BTL: 30-40 ps (~60 ps) at the beginning (end) of life

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ETL PP collision ETL

Different sensor technologies in the sub-detectors because of: larger surface of BTL, different irradiation conditions, different schedules MTD will be divided in 2 sub-detectors

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### LHC / HL-LHC Plan





- Run 1 LS1 EYETS 13 TeV splice consolidation 8 TeV button collimators 7 TeV **R2E** project 2011 2013 2014 2015 2016 ATLAS - CMS upgrade phase 1 ATLAS - CMS experiment HL upgrade beam pipes 2 x nominal Lumi 2 x nominal Lumi 3000 fb<sup>-1</sup> ALICE - LHCb nominal Lumi integrated upgrade 75% nominal Lumi 4000 fb<sup>-1</sup> luminosity BTL ETL
- **BTL** to be installed at the beginning of LHC long shutdown (LS3), before the tracker  $\rightarrow$  now in pre-production phase
- ETL will have more time, installation at the end of shutdown  $\rightarrow$  now moving from prototyping to pre-production

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NFN

iale di Fisica Nucleare







> The CMS MIP Timing Detector

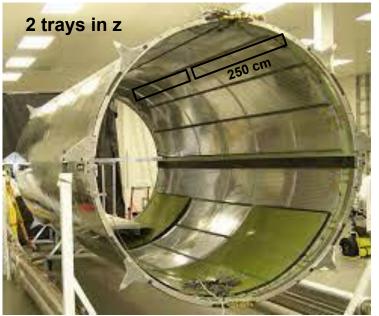
### Status of the Barrel Timing Layer

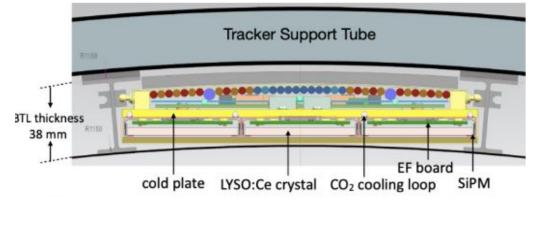
Status of the Endcap Timing Layer



### **BTL design overview**





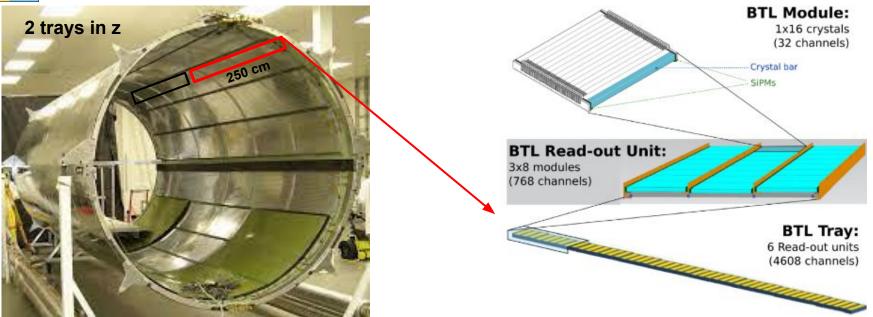


- Thin (~4 cm) cylindrical detector housed inside the tracker support tube
- Made of **72 trays**: 36 (φ) x 2 (z)



### **BTL design overview**





- Thin (~4 cm) cylindrical detector housed inside the tracker support tube
- Made of **72 trays**: 36 (φ) x 2 (z)
- The "building block" is the **BTL module**, made of **1x16 crystals read out by SiPMs**

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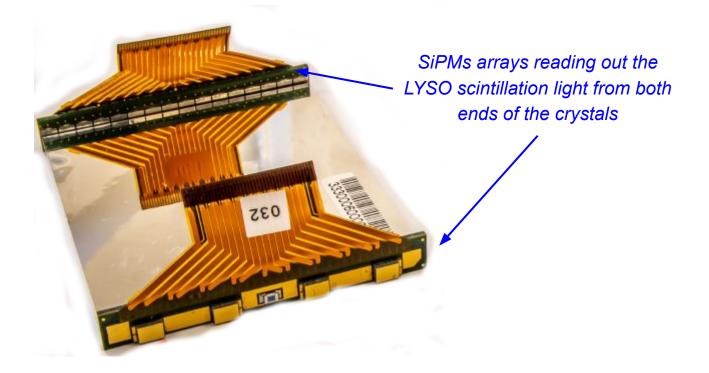


### **BTL sensors**



### LYSO:Ce\* crystal scintillators coupled to silicon photomultipliers (SiPM)

\*Cerium-doped Lutetium Yttrium Orthosilicate





## **BTL sensors**

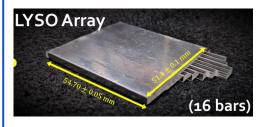


LYSO:Ce\* crystal scintillators coupled to silicon photomultipliers (SiPM)

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#### LYSO:Ce

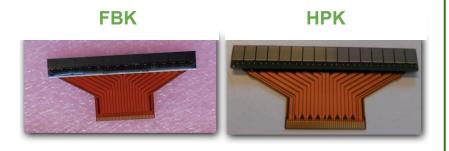
- Well-established technology (PET)
- High light yield: 4000 γ/MeV
- Fast risetime ~ 100 ps
- Radiation hardness proven up to 3e14 n<sub>ed</sub>/cm<sup>2</sup>
- Crystal bar having ~5 cm length, ~3 mm width, variable thickness depending on η



type #1	State.	type #3
3.75 ± 0.03 n		$2.40 \pm 0.03 \ \mathbf{mn}$
	$3.00\pm0.03$ n	

#### SiPM

- Well-established technology
- photon detection efficiency @ LYSO emission peak 20-40 %
- Radiation hardness proven up to 2e14 n<sub>ed</sub>/cm<sup>2</sup>





## **BTL sensors**

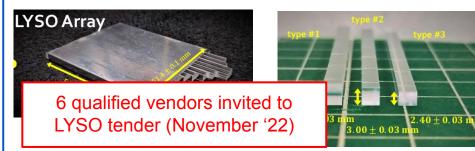


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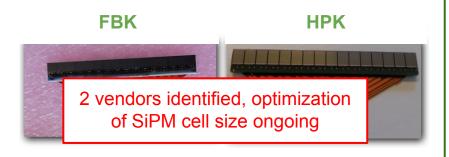
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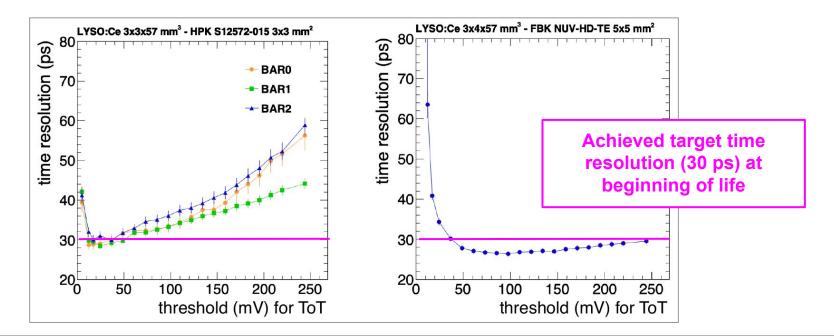




### **Performance of BTL unirradiated sensors**



- > Measured during FNAL test beam with 120 GeV protons
- > Tested crystal bars with 3 different sizes + SiPMs from 2 producers (HPK, FBK)





### **BTL performance evolution with irradiation**

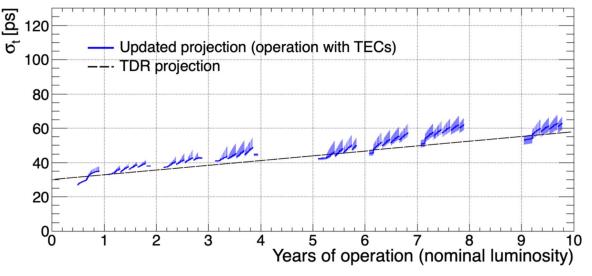


## Performance degradation with irradiation driven by increased dark count rate in SiPMs

Solutions:

- Lower operation voltage, to optimize signal-to-noise ratio
- Use thermoelectric coolers (TECs): operation at -45°C and annealing during HL-LHC shutdowns
- Use SiPMs with larger cell size → increase of photon detection efficiency (PDE)

#### Expected evolution of BTL resolution





### **BTL performance evolution with irradiation**



## Performance degradation with irradiation driven by increased dark count rate in SiPMs

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#### σ<sub>t</sub> [ps] 120 Updated projection (operation with TECs) 100 **TDR** projection 80 What when when the 60 - لملكم للمرالي - المراجع المراجع 40 -20 0 2 3 5 10 Years of operation (nominal luminosity)

→ Thanks to these solutions, the **resolution at end-of-life is within the target (~ 60 ps)** test beams planned in Spring '23

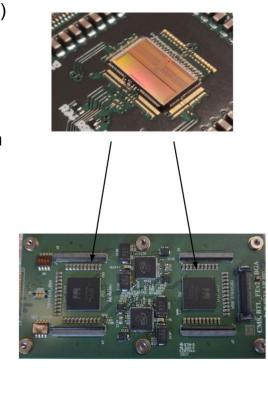
### Expected evolution of BTL resolution

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## **BTL electronics**

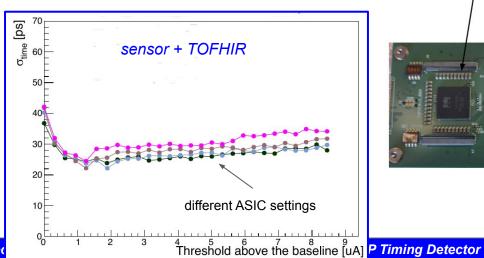




- SiPMs read out by a dedicated ASIC: **TOFHIR** (Time-of-flight, High Rate)
  - 32 independent channels
  - timing measurement
  - amplitude measurement for time walk correction
  - Ongoing engineering run for the production of the latest TOFHIR version (expected end of February '23)

Time resolution as measured with UV laser exciting the LYSO

 $\rightarrow$  within requirements





### **BTL system test and integration**



A large and complex detector like BTL is only made of sensor and ASIC Several activities ongoing to develop system test and integration  $\rightarrow$  we're actually building it!









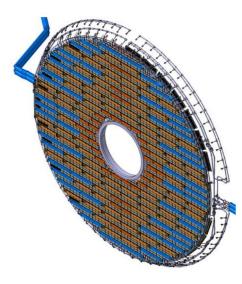
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## **ETL design overview**



- ETL will be mounted on the nose of the CMS CE calorimeter
- 2 double-sided disks for each endcap side, assembled into D's



CMS Phase II Endcap

Endcap region of the CMS detector: ETL will be mounted on the CE nose

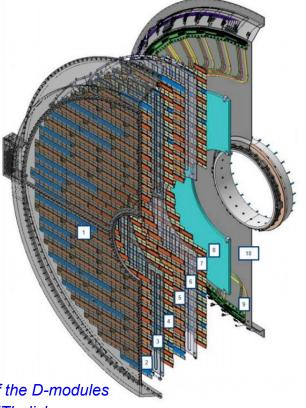
ETL disk



## **ETL design overview**



- ETL will be mounted on the nose of the CMS CE calorimeter
- 2 double-sided disks for each endcap side, assembled into D's
  - <u>double-sided</u> disk → large geometrical acceptance (85% / disk)
  - <u>2 disks</u> to achieve:
    - Single hit time resolution (sensor + ASIC) < 50 ps</li>
    - track time resolution (sensor + ASIC) < 35 ps</p>
- Equipped with 50 um-thick silicon sensors based on the Low-Gain Avalanche Diode (LGAD) technology



Exploded view of one of the D-modules composing the ETL disks

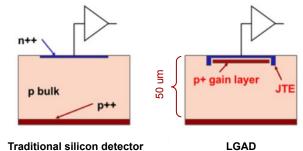


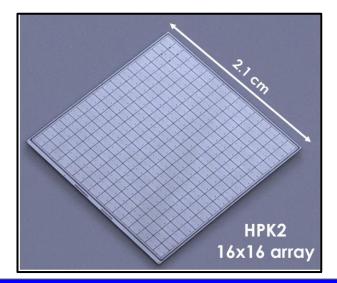
### **Sensors for ETL : the final 16x16**



### The final ETL sensor will be a 16x16 LGAD

- 1.3 x 1.3 mm<sup>2</sup> pads for a total surface of 21.4 x 21.6 mm<sup>2</sup>
- From the beginning to the end of HL-LHC lifetime, sensors expected to:
  - achieve single hit time resolution < 50 ps when coupled to the ASIC (30-40 ps for the bare sensor)
  - deliver > 8 fC of charge
- ETL sensors need also to be **radiation-hard** to survive the harsh radiation environment @ HL-LHC
  - LGADs suited for this: unchanged performance up to 1.5e15 n<sub>eq</sub>/cm<sup>2</sup>



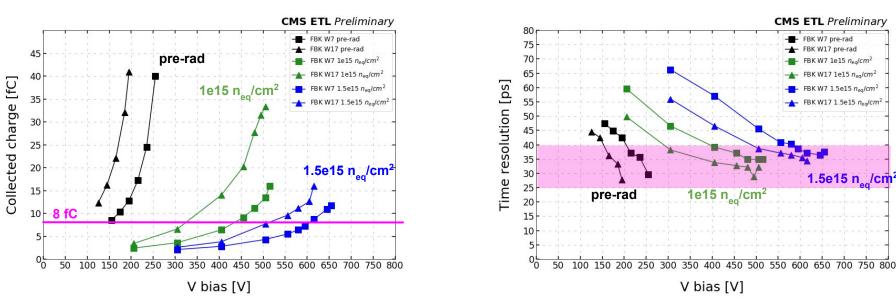




## **Performance of ETL sensors**



- Market Survey for the procurement of the final LGADs for ETL recently completed
  - Identified 4 vendors able to produce the final ETL sensors



#### FBK samples measured with a beta-source setup

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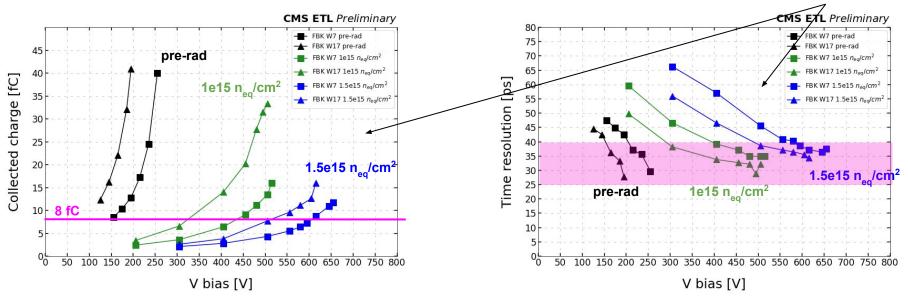
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- Market Survey for the procurement of the final LGADs for ETL recently completed
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Resolution and delivered charge of bare sensors within requirements





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## **ETL electronics**



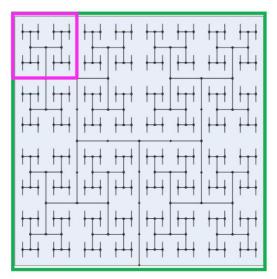
- ETROC is the ETL read-out ASIC
- To achieve time resolution < 50 ps per single hit:
  - low noise + fast rise time
  - power budget: 1 W/chip, 3 mW/channel

### ETROC1

- proved able to reach ~ 40 ps resolution coupled with a prototype LGAD (measured during a test beam with 120 GeV protons)
- Used in the first ETL full system DAQ

#### ETROC2 (full-scale 16x16 ASIC)

- expected in March '23 (test board ready)
- meanwhile, practicing with FPGA-based ETROC2 emulator



- ✓ ETROC0: single analog channel
- ✓ ETROC1: with TDC and 4x4 clock tree
- ETROC2: full functionality + full size
- ETROC3: 16x16 full size chip

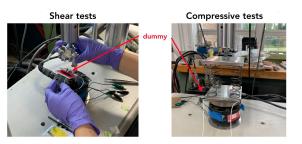


## **ETL system test and integration**

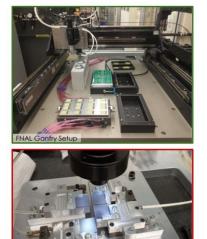


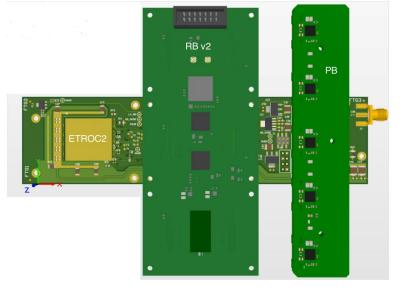
ETL installation coming later than BTL: prototyping just concluded, started working on system test and integration

- We are designing a **testing-optimized module** compatible with ETROC2, read-out board and power board, and with a bump-bonded 16x16 → **will enable a full system test!**
- Practicing with bump-bonding procedure with dummy sensors
- Defining module assembly with gantry / jig















- The CMS MIP Timing Detector will accurately measure charged tracks during the Phase-2 of the experiment at the High-Luminosity LHC
  - MTD divided in 2 sub-detectors: BTL (barrel region) and ETL (endcaps)
- **BTL** will be instrumented with LYSO crystals + SiPMs, read-out by the TOFHIR
  - Beginning of life performance (30-40 ps) within requirements
  - End-of-life performance (~ 60 ps) close to requirements  $\rightarrow$  optimization of SiPM cell size ongoing
  - 6 qualified vendors invited to LYSO tender
  - Engineering run for the production of the TOFHIR2C ASIC ongoing
  - Assembly, integration and full system test progressing well
- **ETL** will be instrumented with LGADs read out by the ETROC
  - Performance at beginning and end of life within requirements (single hit resolution < 50 ps)
  - $\circ$  Sensors market survey recently completed  $\rightarrow$  vendors for the final sensors production identified
  - full-scale 16x16 ETROC2 arriving soon
  - Defining modules assembly, bump-bonding procedure

**Thank You!** 





# **High-Luminosity LHC (HL-LHC)**



- Starting from 2026, LHC will be upgraded
  - will resume operations in 2029, beginning the High-Luminosity era (HL-LHC)
  - Luminosity increase: x3 (instantaneous) / x10 (integrated)



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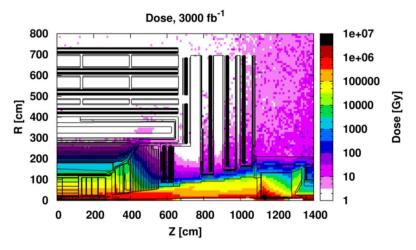
## **Challenges posed by the HL-LHC**

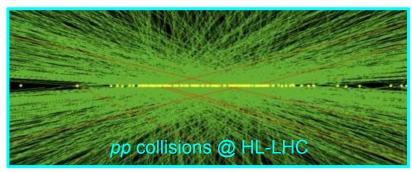


Two main challenges posed to the experiments at the HL-LHC

- **Radiation damage**: annual dose absorbed by detectors at the HL-LHC a factor x10 higher than present LHC
- **Pileup (PU)**: 140-200 interactions overlapping with the hard-scatter interaction expected at each bunch crossing
  - $\circ$  Presently PU ~ 40 at the LHC

To address these challenges, the CMS detector will be upgraded

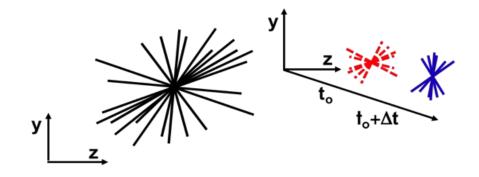








- The MTD task: help CMS to maintain its present performance in the high-luminosity environment
- MTD will provide track timing with ~30 ps resolution



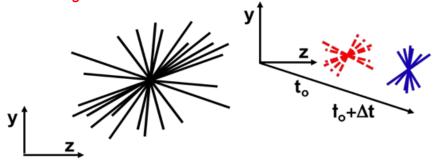






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a single vertex?





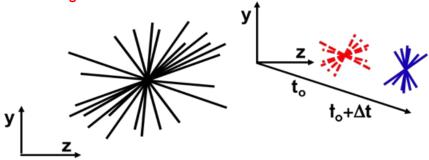


no! 2 vertices overlapped

in space, but not in time

- The MTD task: help CMS to maintain its present performance in the high-luminosity environment
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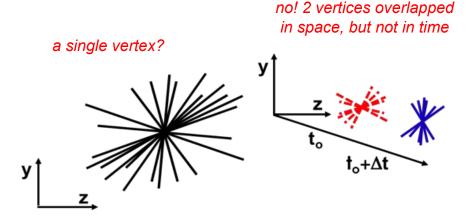
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- The MTD task: help CMS to maintain its present performance in the high-luminosity environment
- MTD will provide track timing with ~30 ps resolution
  → slice the bunch crossing temporal structure in
  - $\sim$  30 ps time exposures



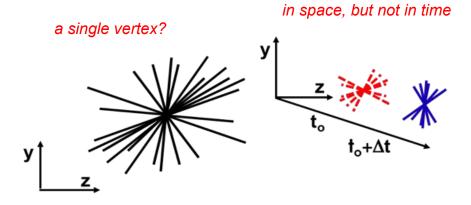


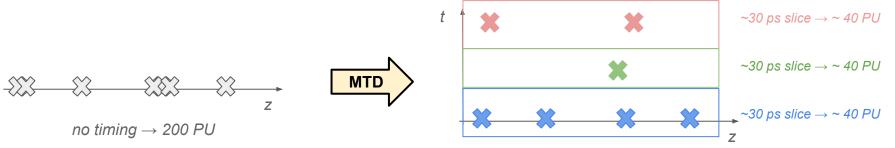


no! 2 vertices overlapped

- The MTD task: help CMS to maintain its present performance in the high-luminosity environment
- MTD will provide track timing with ~30 ps resolution
  → slice the bunch crossing temporal structure in
  ~ 30 ps time exposures
- The number of concurrent interactions in a 30 ps exposure drops by a factor 5-6



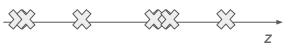




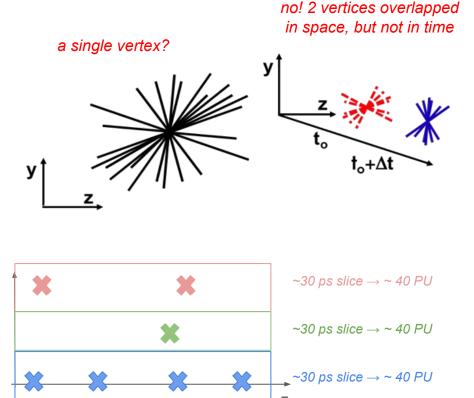




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- MTD will provide track timing with ~30 ps resolution
  → slice the bunch crossing temporal structure in
  ~ 30 ps time exposures
- The number of concurrent interactions in a 30 ps exposure drops by a factor 5-6
  - PU level drops from 200 to  $40 \rightarrow$  with MTD, we can restore the present PU condition



no timing  $\rightarrow$  200 PU



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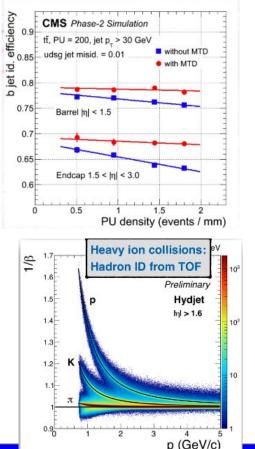
MTD



# Impact of MTD on physics performance

Just a glimpse: list of improvements too long to go through every item in this talk

- Fraction of vertices merged during reconstruction drops from 15% to 1% (shift from 3D-reco to 4D-reco) → improvements in physics object identification and reconstruction (b-tagging, lepton isolation, missing energy)
- Up to 30% reduction of spurious secondary vertices → 3-5% increase in b-tagging efficiency
  - $\circ \quad \text{HH} \rightarrow \text{4b: 18\% increase in signal yield}$
- MTD will also add new capability to CMS: e.g. particle identification of low-p<sub>T</sub> charged hadrons thanks to time-of-flight measurements
  - important for heavy-ion physics





## **BTL time resolution**



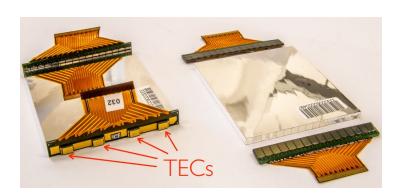
$$\sigma_{t}^{BTL} = \sigma_{t}^{clock} \oplus \sigma_{t}^{digi} \oplus \sigma_{t}^{ele} \oplus \sigma_{t}^{phot} \oplus \sigma_{t}^{DCR}$$

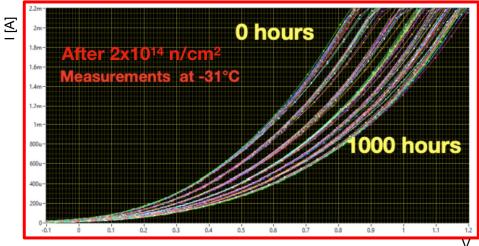
- BTL time resolution main contributors are:
  - $\circ$  electronics noise
  - $\circ$  photo-statistics
  - SiPMs Dark Count Rate (DCR)



### BTL performance evolution with irradiation

- Istituto Nazionale di Fisica Nucleare
- Sensors performance degradation with irradiation driven by increased dark count rate (DCR) in SiPMs
- Solutions to cope with it:
  - Lower operation voltage, to optimize signal-to-noise ratio
  - Noise filtering with signal processing technique in TOFHIR
  - Use thermoelectric coolers (TECs): enable SiPM operation at -45°C (lower noise) and annealing at +40°C during HL-LHC shutdowns (beneficial for the dark current)



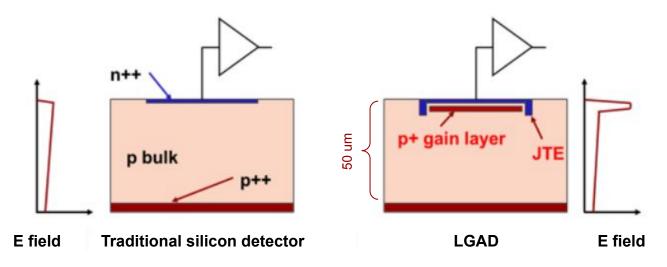




### **Sensors for ETL : LGAD**



- 50 µm-thick silicon sensors based on the Low-Gain Avalanche Diode (LGAD) technology
  - $p^+$  gain layer implanted underneath  $n^{++}$  electrode
  - electron charge multiplication for E > 300 kV/cm
  - moderate internal gain: 10-30
- Thin sensor + LGAD technology  $\rightarrow$  excellent timing performance

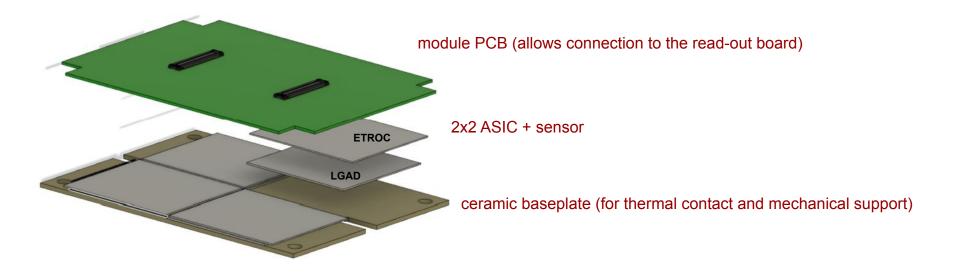




## **ETL design overview**



#### ETL will be populated with modules $\rightarrow$ the "building block" of the ETL disks





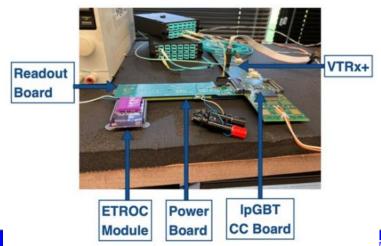
## **ETL electronics**

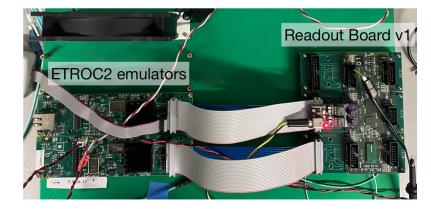


The full-size 16x16 ETROC2 expected in March '23  $\rightarrow$  several activities ongoing while waiting for it

Established 1st generation system based on ETROC1 (4x4)

- full system DAQ using ETROC1
- Signal can come from either internal charge injected with ETROC chip or from the LGAD sensor





 FPGA-based emulation of ETROC2: enable development of DAQ and testing of readout board in advance of ETROC2